

承認書

Specification For Approval

Customer	:(客戶) 						
Descriptio	n: (產品描述)						
Part numbe	r: (產品型號) 	TJ-S1615RB06YJY-A3					
Date	(日期)						
Approved By: (客戶承認)							
	Approval	Check	Design	Sales			
	核准	審核	製作	業務			

 Customer Service Hotline:
 400-676-8616

 TEL:
 0769-8662 5999
 0769-8200 2226

 E-MIAL:
 dg@togialed.com

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Features

1.6mm x 1.5mm SMT LED, 0.6mm thickness

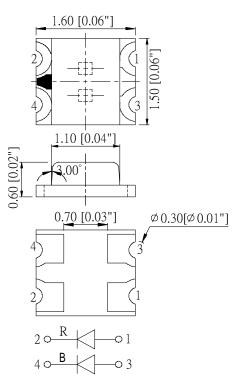
Low power consumption

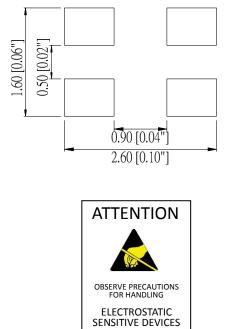
- Wide view angle
- Package: 4000pcs/reel
- **RoHS** Compliant

Applications

- Ideal for back light and indicator
- Various colors and lens types available

Package outlines





Recommend Pad Layout

Part No.	Emitted color	Dice	Lens color
	Red	AlGaInP	
TJ-S1615RB06YJY-A3	Blue	InGaN/GaN	Water transparent

Notes:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ± 0.1 mm (0.004inch) unless otherwise noted.



Absolute Maximum Ratings (TA=25°C)

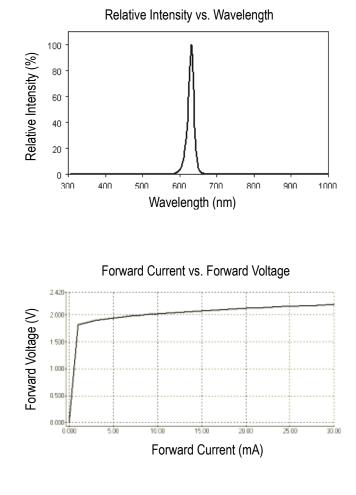
Deremeter	Cumb al	Value		Unit		
Parameter	Symbol	R B				
Power dissipation	Pd	72	111	mW		
Forward current	lf	30		mA		
Reverse voltage	Vr	5		V		
Operating temperature	Тор	-40 ~+80		°C		
Storage temperature	Tstg	-40 ~+85		-40 ~+85 ℃		°C
Peak pulsing current (1/8 duty f=1kHz)	lfp	125		mA		

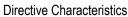
Electro-Optical Characteristics (TA=25°C)

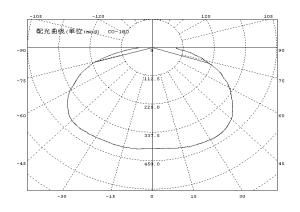
Parameter	Test	Symbol		Value			Unit
T arameter	Condition			Min	Тур	Max	Onit
Wavelength at peak emission	lf=20mA	λр	R B		630 465	1 1	nm
Spectral half bandwidth	lf=20mA	Δλ	R B		18 25		nm
Dominant wavelength	lf=20mA	λd	R B	620 460		630 470	nm
Forward voltage	lf=20mA	Vf	R B	1.8 2.8		2.4 3.4	V
Luminous intensity	lf=20mA	lv	R B	80 80		200 200	mcd
Viewing angle at 50% lv	lf=10mA	2 0 1	/2		120		Deg
Reverse current	Vr=5V	Ir				10	μA



Optical Characteristic Curves (Red)

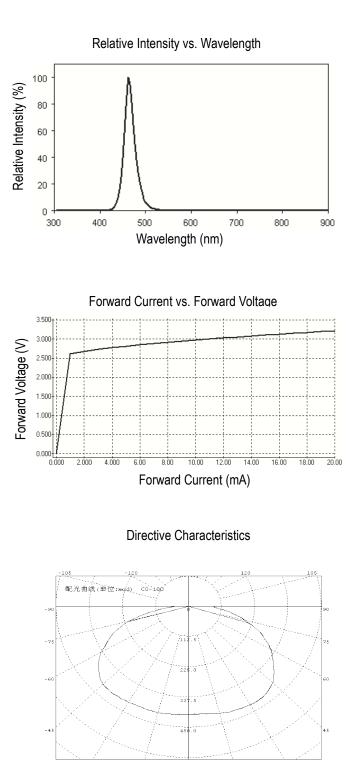






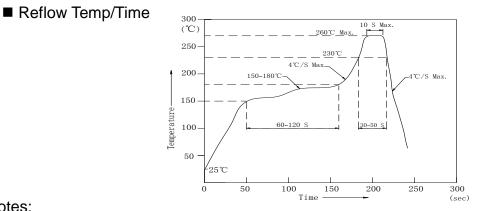


Optical characteristic curves (Blue)





Reflow Profile



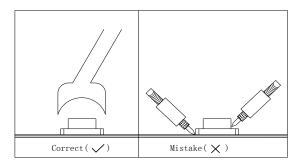
Notes:

- 1.We recommend the reflow temperature $245^{\circ}C(\pm 5^{\circ}C)$. the maximum soldering temperature should be limited to 260 °C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3.Number of reflow process shall be 2 times or less.
- ■Soldering iron

Basic spec is \leq 5sec when 320°C(±20°C). If temperature is higher, time should be shorter(+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 350°C.

Rework

- 1.Customer must finish rework within 5 sec under 340°C.
- 2. The head of iron cannot touch copper foil
- 3. Twin-head type is preferred.

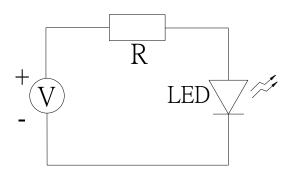


Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.



Test Circuit and Handling Precautions

Test circuit



- Handling precautions
- 1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
- 2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°℃~30°℃(41°F~86°F)

- 2.2 Shelf life in sealed bag: 12 month at <5°C ~30°C and <30% R.H. after the package is Opened, the products should be used within a week or they should be keeping to stored at ≤20 R.H. with zip-lock sealed.
- 3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as followings:

- 3.1 60 \pm 3°C x(12~24hrs) and <5%RH, taped reel type
- 3.2 100 \pm 3°C x(45min~1hr), bulk type
- 3.3 130±3℃ x(15~30min), bulk type



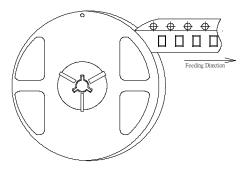
Test Items and Results of Reliability

Туре	Test Item	Test Conditions	Note	Number of Damaged
	Temperature Cycle	-40°C 30min ↑ →(25°C/5min)↓ 100°C 30min	100 cycle	0/22
	Thermal Shock	-40℃ 15min ↑↓ 100℃ 15min	100 cycle	0/22
mental ence	High Humidity Heat Cycle	30℃⇔ 65℃ 90%RH 24hrs/1cycle	10 cycle	0/22
Environmental Sequence	High Temperature Storage	Ta=100℃	1000 hrs	0/22
	Humidity Heat Storage	Ta=60 ℃ RH=95%	1000 hrs	0/22
	Low Temperature Storage	Ta=-40℃	1000 hrs	0/22
Operation Sequence	Life Test	Ta=25℃ IF=20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60℃ RH=95% IF=10mA	500 hrs	0/22
	Low Temperature Life Test	Ta=-20℃ IF=20mA	1000 hrs	0/22

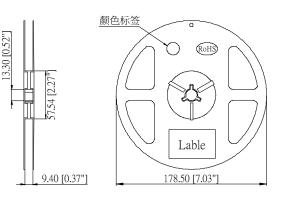


Series SMD Chip LED Lamps Packaging Specifications

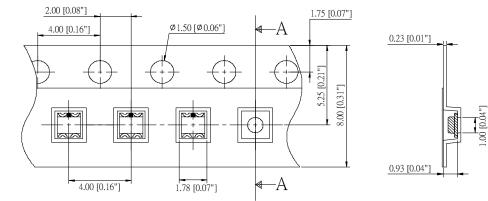
• Feeding Direction



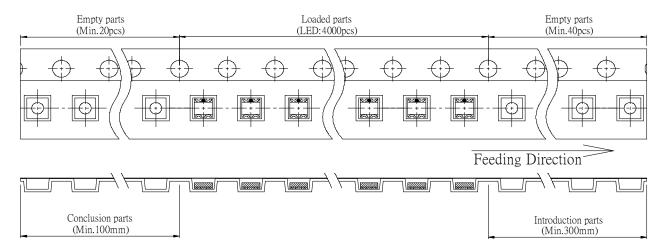
• Dimensions of Reel (Unit: mm)



• Dimensions of Tape (Unit: mm)



• Arrangement of Tape



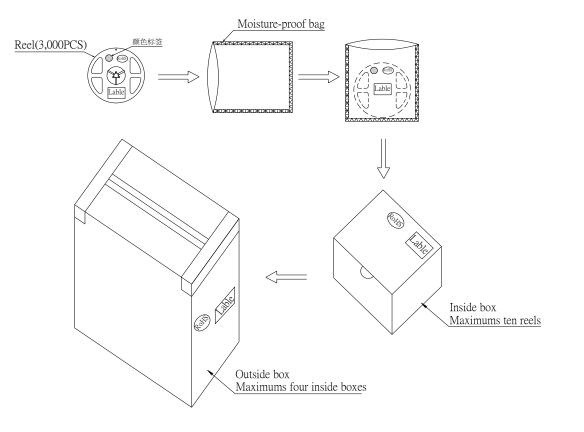
Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.



Series SMD Chip LED Lamps Packaging Specifications

• Packaging specifications



Notes:

Reeled products (numbers of products are 4,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, ten moisture-proof bag of maximums (total maximum number of products are 40,000pcs) packed in an inside box (about size: 240x 220x 120mm) and four inside boxes of maximums are put in the outside box (about size: 460mm x 246mm x 250mm) Together with buffer material, and it is packed. (Part No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. and quantity should appear on the label on the cardboard box.) The number of the loading steps of outside box (cardboard box) has it to three steps.